Accepted Manuscript

Ultra-low thermal conductivity on Si/Au multilayer films with metal layer thickness below 8 nm

Superlattices

and Microstructures

Yangsen Hu, Zhiyu Hu

PII: S0749-6036(17)31526-4

DOI: 10.1016/j.spmi.2017.08.034

Reference: YSPMI 5209

To appear in: Superlattices and Microstructures

Received Date: 21 June 2017

Revised Date: 18 August 2017

Accepted Date: 23 August 2017

Please cite this article as: Yangsen Hu, Zhiyu Hu, Ultra-low thermal conductivity on Si/Au multilayer films with metal layer thickness below 8 nm, *Superlattices and Microstructures* (2017), doi: 10.1016/j.spmi.2017.08.034

This is a PDF file of an unedited manuscript that has been accepted for publication. As a service to our customers we are providing this early version of the manuscript. The manuscript will undergo copyediting, typesetting, and review of the resulting proof before it is published in its final form. Please note that during the production process errors may be discovered which could affect the content, and all legal disclaimers that apply to the journal pertain.

ACCEPTED MANUSCRIPT

Ultra-low thermal conductivity on Si/Au multilayer films with metal layer thickness below 8 nm

Yangsen Hu*, Zhiyu Hu*

National Key Laboratory of Science and Technology on Micro/Nano Fabrication,

Department of Micro/Nano Electronics, School of Electronic Information and Electrical Engineering,

Shanghai Jiao Tong University, Shanghai 200240, China

*Corresponding author's e-mail address: hys106102@hotmail.com(Yangsen Hu) zhiyuhu@sjtu.edu.cn (Zhiyu Hu)

Download English Version:

https://daneshyari.com/en/article/7940197

Download Persian Version:

https://daneshyari.com/article/7940197

Daneshyari.com